

## General Description

The Sanrise SRC60R125B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R125B break down voltage is 600V and it has a high rugged avalanche characteristics. The SRC60R125B is available in TO-247 package.

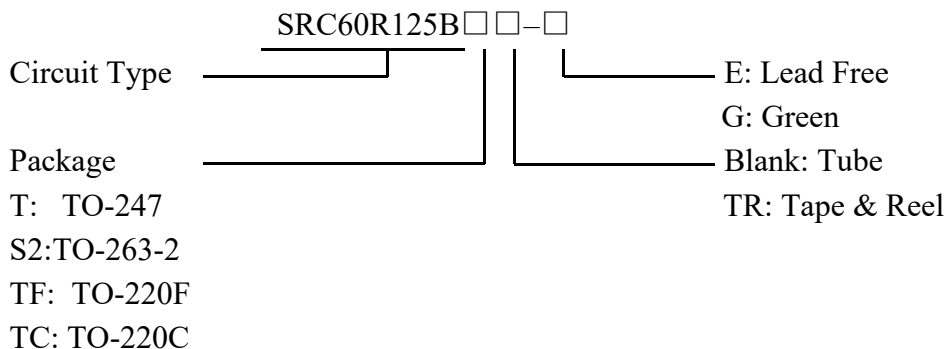
## Features

- Ultra Low  $R_{DS(ON)} = 125m\Omega @ V_{GS} = 10V$ .
- Ultra Low Gate Charge,  $Q_g = 57.3nC$  typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance

## Application

- EV Charger
- Sever / Telecom

## Ordering Information



## Symbol

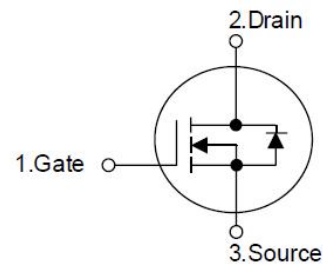


Figure 1 Symbol of SRC60R125B

## Package Type

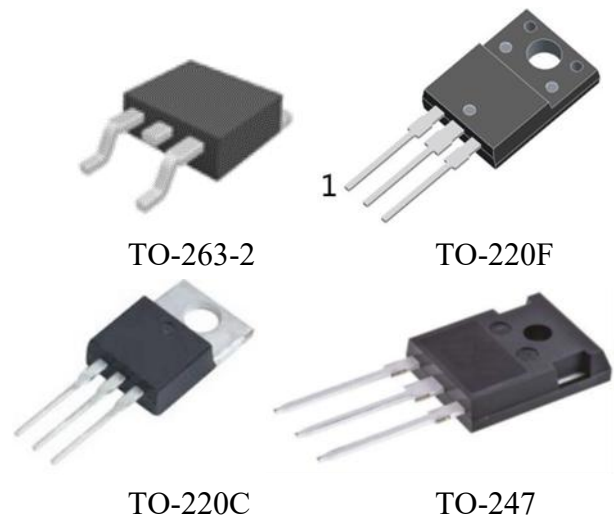


Figure 2 Package Type of SRC60R125B

Package	Part Number	Marking ID	Packing Type
TO-247	SRC60R125BT-G	SRC60R125BTG	Tube
TO-263-2	SRC60R125BS2TR-G	SRC60R125BS2G	Tape & Reel
TO-220F	SRC60R125BTF-G	SRC60R125BTFG	Tube
TO-220C	SRC60R125BTC-G	SRC60R125BTCG	Tube

## Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DSS}$	600	V
Gate-Source Voltage (static)		$V_{GSS}$	±20	V
Gate-Source Voltage (dynamic), AC ( $f > 1$ Hz)		$V_{GSS}$	±30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	26.2	A
	$T_C = 125^\circ\text{C}$		11.7	
Pulsed Drain Current (Note 2)		$I_{DM}$	78.6	A
Avalanche Energy, Single Pulse (Note 3)		$E_{AS}$	340	mJ
Avalanche Energy, Repetitive (Note 2)		$E_{AR}$	0.4	mJ
Avalanche Current, Repetitive (Note 2)		$I_{AR}$	2.5	A
Continuous Diode Forward Current		$I_S$	26.2	A
Diode Pulse Current		$I_{S,PULSE}$	78.6	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$		dv/dt	50	V/ns
Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}$ , $I_{SD} \leq I_D$		dv/dt	50	V/ns
Operating Junction Temperature		$T_J$	150	°C
Storage Temperature		$T_{STG}$	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3.  $I_{AS} = 2.5\text{A}$ ,  $V_{DD} = 60\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

## Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-220F	$R_{thJC}$			3.7	°C /W
	TO-220C				0.69	
	TO-247				0.69	
	TO-263				0.69	
Thermal resistance, Junction-to-Ambient	TO-220F	$R_{thJA}$			80	°C /W
	TO-220C				62	
	TO-247				62	
	TO-263				62	

**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=600V, V_{GS}=0V$			10	$\mu A$
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	3.0	4.0	5.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=13A$		106	125	$m\Omega$
Gate Resistance	$R_G$	$f=1MHz, \text{Open Drain}$		1.5		$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		2.2		nF
Output Capacitance	$C_{OSS}$			88		pF
Reverse Transfer Capacitance	$C_{RSS}$			1.4		
Effective output capacitance, energy related <sup>NOTE5</sup>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 400V$		48.7		pF
Effective output capacitance, time related <sup>NOTE6</sup>	$C_{O(tr)}$			284.8		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=13A, R_G=5.3\Omega, V_{GS}=10V$		13		ns
Rise Time	$t_r$			11		
Turn-off Delay Time	$t_{d(off)}$			53		
Fall Time	$t_f$			6		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{DD}=480V, I_D=13A, V_{GS}=0 \text{ to } 10V$		13.6		nC
Gate to Drain Charge	$Q_{gd}$			28.0		
Gate Charge Total	$Q_g$			57.3		
Gate Plateau Voltage	$V_{plateau}$			6.1		V
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=13A$		0.9	1.1	V
Reverse Recovery Time	$t_{rr}$	$V_R=100V, I_F=13A, dI_F/dt=100A/\mu s$		122		ns
Reverse Recovery Charge	$Q_{rr}$			0.59		$\mu C$
Peak Reverse Recovery Current	$I_{rrm}$			9.6		A

Note:

- $C_{O(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 400V
- $C_{O(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 400



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